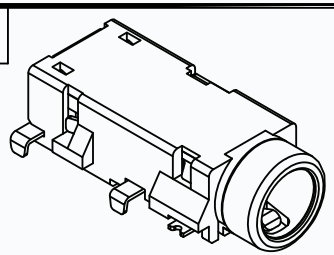
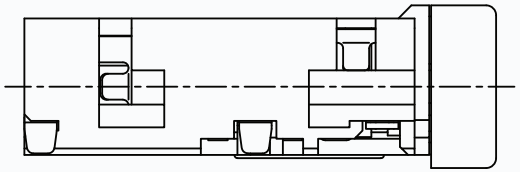
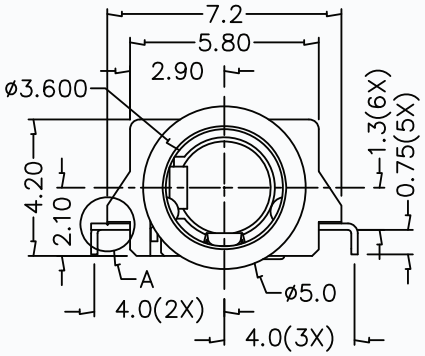
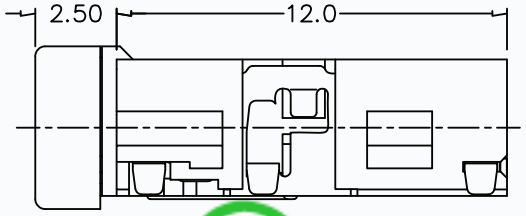
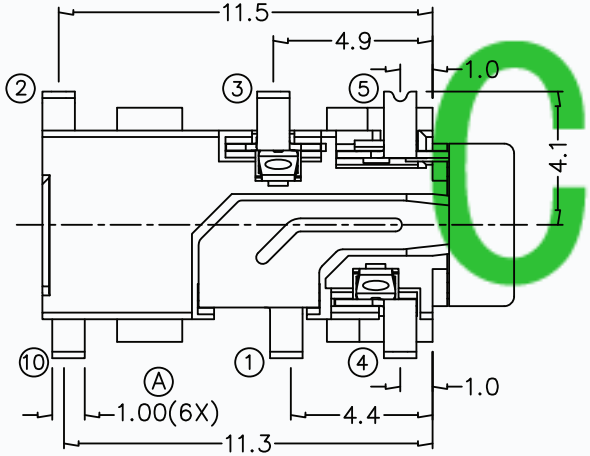
CAD FILE:

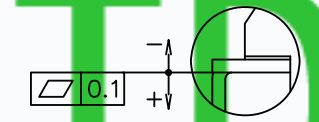


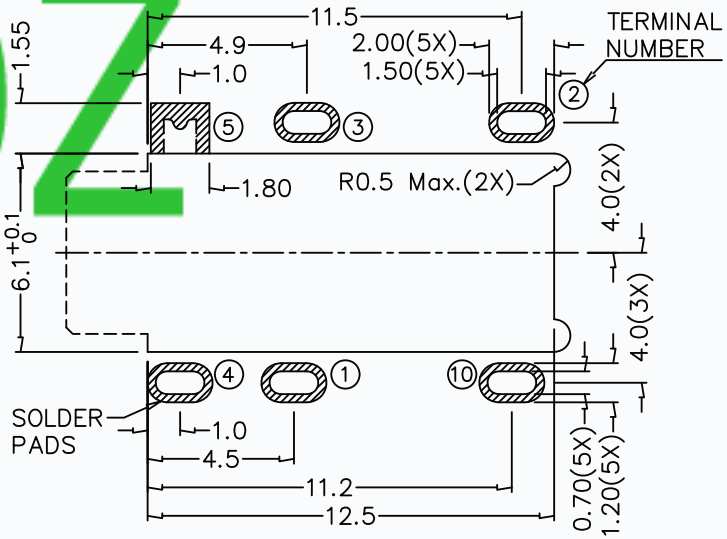




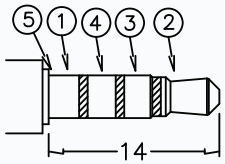



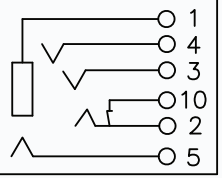




RECOMMENDED SOLDER PAD LAYOUT (TOP VIEW)




ø3.5 MATE PLUG

| MODEL NO. | T13-35342D |
|---|---|
| SCHEMATIC |  |



## * MATERIAL

TERMINAL 1 : COPPER ALLOY
TERMINAL 2 : COPPER ALLOY
TERMINAL 3 : COPPER ALLOY
TERMINAL 4 : COPPER ALLOY
TERMINAL 5 : STAINLESS STEEL
TERMINAL 10 : COPPER ALLOY
BUSHING : BRASS
HOUSING : PA6T

CMTDDZ

| | | | | | | |
|---|---|---|---|---|---|---|
| | | TOLERANCE UNLESS SPECIFIED WITHIN 1.5mm : ±0.1mm OVER 1.5mm : ±0.2mm | THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF DONGGUAN TIANDU ELECTRONICS CO.,LTD. AND SHALL NOT BE REPROOUCED. COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF DONGGUAN TIANDU ELECTRONICS CO., LTD | TITLE : 3.5mm SMD PHONE JACK | UNIT : mm | DRWG NO.: CMTDDZ-T13-35342-00 | |
| | | | | MODEL: T13-35342D | SCALE: 3:1 | DWN. ERIC 2013-6-17 | |
| APPD. | DESCRIPTIONS OF REVISION | | | CMTDDZ 东莞市田都电子有限公司 DONGGUAN TIANDU ELECTRONICS CO.,LTD. | | CHK'D MAIKO 2013-6-17 | |
| | | | | | | APPD. Coco 2013-6-17 | |